

## 1.2MHZ Step-up DC/DC Converter in SOT23-6

### **GENERAL DESCRIPTION**

The XR1151 step-up switching regulator generates an output voltage of up to 6V from an input voltage as low as 1.6V. Ideal for applications where space is limited, it switches at 1.2MHz, allowing the use of tiny, low cost and low profile external components. Its internal 2A,  $100 \text{m}\Omega$ NMOS switch provides high efficiency even at heavy load, while the constant frequency, current mode architecture results in low, predictable output noise that is easy to filter. Internal frequency compensation is designed to accommodate ceramic output capacitors, further reducing noise. The device features very low shutdown current of 0 5uA

The XR1151 is available in the 6-lead SOT-23 package.

### **FEATURES**

- Internal 2A MOSFET Switch
- 1.2MHZ Switching Frequency
- Integrated Soft-Start
- Low 1.6V Vin Operation
- Low  $R_{ds(on)}$ Switch :100m $\Omega$  at 5V Output
- Delivers 5V at 800mA from a 3.3V input
- Delivers 3V at 800mA from a 2.5V input
- Uses Small.Low Profile External Components
- Low profile(1mm):SOT-23(Thin SOT)package

### **APPLICATIONS**

- White LED Driver Supply
- Local 3.3V or 5V supply
- Battery Back-up

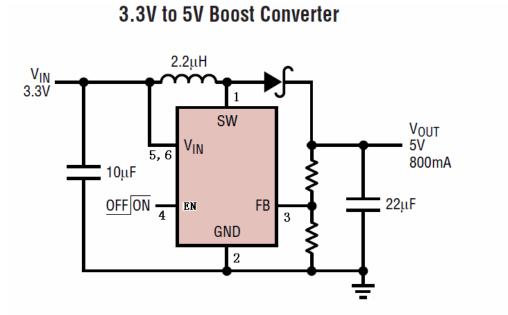


Figure 1. Typical Application Circuit



### **ORDERING INFORMATION**

PART NUMBER	TEMP RANGE	SWICHING FREQUENCY	OUTPUT VOLTAGE (V)	CURRENT LIMIT(A)	PACKAGE	PINS
XR1151	-40°C to 85°C	1.2MHz	Adjustable	2	SOT23-6	6

### **PIN CONFIGURATION**

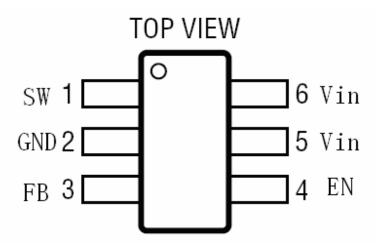


Figure 2. PIN Configuration

## **PIN DESCRIPTION**

PIN NUMBER	PIN NAME	PIN DESCRIPTION
1	Switch Output. Connect this pin to the inductor.	
2 GND Ground.		
3 FB Feedback Input. The voltage at this pin is regulated to 0.6V. Connect to divider between output and ground to set output voltage		Feedback Input. The voltage at this pin is regulated to 0.6V. Connect to the resistor divider between output and ground to set output voltage
4 EN Enable Input. When higher than 1.5V, this pin turns the IC on. When lower this pin turns the IC off.		Enable Input. When higher than 1.5V, this pin turns the IC on. When lower than 0.3V, this pin turns the IC off.
5 Vin Power Supply		Power Supply
6 Vin Power Supply		Power Supply

## **ABSOLUTE MAXIMUM RATINGS**

(Note: Do not exceed these limits to prevent damage to the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.)

PARAMETER	VALUE	UNIT	
Supply Voltage VIN	-0.3 to 6.5	V	



FB, EN Voltage	-0.3 to VIN+0.3	V
SW Voltage	-0.3 to VIN+0.3	V
Operating Ambient Temperature	-40 to 85	С°
Maximum Junction Temperature	125	°C
Storage Temperature	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)	300	°C

# **ELECTRICAL CHARACTERISTICS**

(V<sub>IN</sub> = 3.6V,  $T_A$ = 25°C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
Input Voltage Range	V <sub>IN</sub>		1.6		6.0	V
Quiescent Current		V <sub>FB</sub> =0.7V EN=Vin, I <sub>Load</sub> =0		65		
Shutdown Current	lq	V <sub>EN</sub> =0V, V <sub>IN</sub> =3.3V		0.5		uA
		T <sub>a</sub> =25°C	0.588	0.6	0.612	
Regulated Feedback Voltage	$V_{\text{FB}}$	0< T <sub>a</sub> < 85°C	0.6865	0.6	0.6135	V
		-40°C < T <sub>a</sub> <85°C	0.585	0.6	0.615	
Reference Voltage Line Regulation		V <sub>IN</sub> =1.6V to 5.5V		0.05	0.5	%
Output Voltage Load Regulation				0.5		%
Current Limit	I <sub>PEAK</sub>			2	2.4	А
Oscillator Frequency	F <sub>osc</sub>	V <sub>FB</sub> =0.6V or V <sub>OUT</sub> =100%		1.2		MHz
Rds(ON) of N-channel FET		I <sub>SW</sub> =-100mA		100		Ohm
Enable Threshold		V <sub>IN</sub> = 1.6V to 5.5V	0.3	1	1.5	V
Enable Leakage Current			-0.1		0.1	μA
SW Leakage Current		$V_{EN}$ = 0V, $V_{SW}$ = 0V or 5V, $V_{IN}$ = 5V			1	uA



XR1151

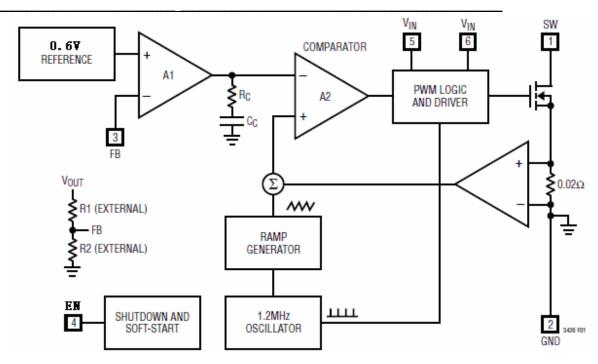


Figure 3. Functional Block Diagram

### **FUNCTIONAL DESCRIPTION**

#### NORMAL OPERATION

The XR1151 is a monolithic 1.2MHz boost converter housed in a 6-lead SOT-23 package. The device features fixed frequency, current mode PWM control for excellent line and load regulation. The low

 $R_{ds(on)}$  NMOS switch enables the device to maintain

high efficiency over a wide range of load current. Operation of the feedback loop which sets the peak inductor current to keep the output in regulation can be best understood by referring to the Block Diagram in Figure 1. At the start of each clock cycle a latch in the PWM logic is set and the NMOS switch is turned on. The sum of a voltage proportional to the switch current and a slope compensating voltage ramp is fed to the positive input to the PWM comparator. When this voltage exceeds either a voltage proportional to the 2A current limit or the PWM control voltage, the latch in the PWM logic is reset and NMOS switch is turned off. The PWM

### **APPLICATION INFORMATION**

#### INDUCTOR SELECTION

The XR1151 can utilize small surface mount

control voltage at the output of the error amplifier is the amplified and compensated difference between the feed- back voltage on the FB pin and the internal reference voltage of 0.6V. If the control voltage increases, more current is delivered to the output. When the control voltage exceeds the ILIMIT reference voltage, the peak current is limited to a minimum of 2A. The current limit helps protect the XR1151 internal switch and external components connected to it. If the control voltage decreases, less current is delivered to the output. During load transients control voltage may decrease to the point where no switching occurs until the feedback voltage drops below the reference. The XR1151 has an integrated soft-start feature which slowly ramps up the feedback control node from 0V. The soft-start is initiated when EN is pulled high.

inductors due to its 1.2MHz switching frequency. A 2.2 $\mu$ H or 4.7 $\mu$ H inductor will be the best choice for

XySemi Inc

www.xysemi.com REV0.1b



most XR1151 applications.

The inductor should have low DCR (DC resistance) to reduce the I2R power losses, and must be able to handle the peak inductor current without saturating.

Several inductor manufacturers are listed in Table 1 Selected inductor by actual application:

Manuf acture r	Part Number	Induct ance( uH)	DRC max (Ohm s)	Dimension s L*W*H(mm 3)
Murata	LQH5B PN	2.2	0.03	5*5*2
	LQH32P N	2.2	0.06	3.2*2.5*1.7
Sumid	CDRH3	2.2	0.03	4*4*1.8
а	D16	4.7	0.07	

Table 1. Recommend Surface Mount Inductors

#### **Diode Selection**

A Schottky diode is recommended for use with the XR1151.Use of a low forward voltage diode such as the ON Semiconductor MBRA210LT3 is recommended. A Schottky diode rated at 2A is recommended for use with the XR1151.

#### **INPUT CAPACITOR SELECTION**

The input capacitor reduces input voltage ripple to the converter, low ESR ceramic capacitor is highly recommended. For most applications, a 10~22uF capacitor is used. The input capacitor should be placed as close as possible to VIN and GND. Recommended: Murata GRM32ER61A106KA01L

Murata GRM32NR61A226KE19L

#### **OUTPUT CAPACITOR SELECTION**

A low ESR output capacitor is required in order to maintain low output voltage ripple. In the case of ceramic output capacitors, capacitor ESR is very small and does not contribute to the ripple, so a lower capacitance value is acceptable when ceramic capacitors are used. A 22uF ceramic output capacitor is suitable for most applications.

Recommended: Murata GRM32NR61A226KE19L

#### **OUTPUT VOLTAGE PROGRAMMING**

In the adjustable version, the output voltage is set by a resistive divider according to the following equation:

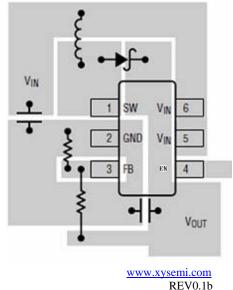
$$R_2 = R_1 \times \left(\frac{V_{OUT}}{0.6} - 1\right)$$

Typically choose R1=100K and determine R2 from the following equation:

Connect a small capacitor across R1 feed forward capacitance at the FB pin for better performance.

#### **PCB Layout Guidelines**

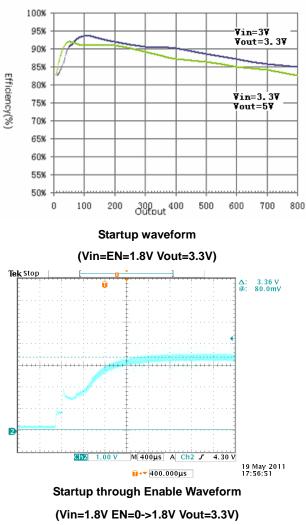
The high speed operation of the XR1151 demands careful attention to board layout. You will not get advertised performance with careless layout. Figure as below shows the recommended component placement. A large ground pin copper area will help to lower the chip temperature.

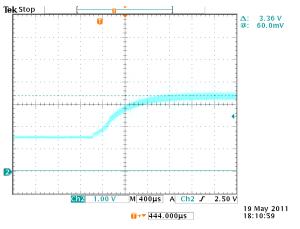




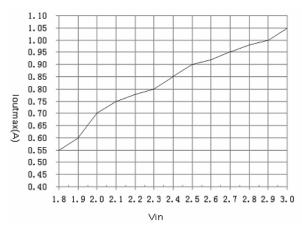
## TYPICAL PERFORMANCE CHARACTERISTICS

#### Efficiency vs. Output Current

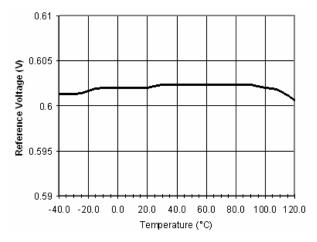




#### IOUT(MAX) vs VIN(Vout=3.3V)



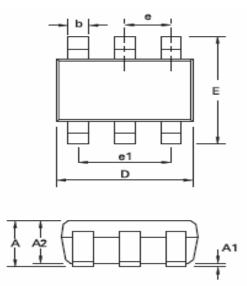
**Reference Voltage vs. Temperature** 

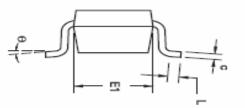


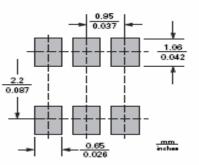


### PACKAGE OUTLINE

### SOT23-6 PACKAGE OUTLINE AND DIMENSIONS







DIM	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
A	0.90	1.45	0.0354	0.0570	
A1	0.00	0.15	0.00	0.0059	
A2	0.90	1.30	0.0354	0.0511	
b	0.35	0.50	0.0078	0.0196	
С	0.09	0.26	0.0035	0.0102	
D	2.70	3.10	0.1062	0.1220	
E	2.20	3.20	0.0866	0.1181	
E1	1.30	1.80	0.0511	0.0708	
L	L 0.10		0.0039	0.0236	
е	0.95 REF 1.90 REF		0.0374 REF		
e1			0.0748 REF		
L	0°	30°	0°	30°	

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Isolated DC/DC Converters category:

Click to view products by XySemi manufacturer:

Other Similar products are found below :

 FMD15.24G
 PSL486-7LR
 Q48T30020-NBB0
 18362
 JAHW100Y1
 SPB05C-12
 SQ24S15033-PS0S
 18952
 19-130041
 CE-1003
 CE-1004

 RDS180245
 MAU228
 J80-0041NL
 DFC15U48D15
 XGS-1205
 NCT1000N040R050B
 SPB05B-15
 SPB05C-15
 L-DA20
 DCG40-5G

 QME48T40033-PGB0
 AK1601-9RT
 DPA423R
 VI-R5022-EXWW
 PSC128-7iR
 RPS8-350ATX-XE
 DAS1004812
 PQA30-D24-S24-DH
 vi 

 m13-cw-03
 VI-LN2-EW
 VI-PJW01-CZY
 CK2540-9ERT
 AK-1615-7R
 700DNC40-CON-KIT-8G
 350DNC40-CON-KIT-9G
 088-101348-G

 VI-L52-EW
 VI-L53-CV
 PQA30-D48-S12-TH
 VI-L50-IY
 VI-LC63-EV
 AM2D-051212DZ
 24IBX15-50-0ZG
 HZZ01204-G
 SPU02L-09

 SPU02M-09
 SPU02N-09
 UNO-PS/350-900DC/24DC/60W
 QUINT4-BUFFER/24DC/20
 MA2D-051212DZ
 24IBX15-50-0ZG
 HZZ01204-G
 SPU02L-09